

**Amendments to the Claims:**

Please amend claims 1, 14, 21, 34-42 as follows. Following is a complete listing of the claims pending in the application, as amended:

1. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:
  - a workpiece holder configured to receive a microelectronic workpiece;
  - a workpiece electrode configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
  - a first remote electrode and a second remote electrode, the first and second remote electrodes being spaced apart from the workpiece holder;
  - a mechanical medium having a bearing surface facing the workpiece holder and a backside facing the first and second remote electrodes;
  - a switching assembly coupled to the workpiece electrode, the first remote electrode, and the second remote electrode;
  - an AC power supply electrically coupled to the switching assembly to be in electrical communication with the first and second remote electrodes via the switching assembly; and
  - a DC power supply electrically coupled to the switching assembly to be in electrical communication with the workpiece electrode at one polarity and at least one of the first and second remote electrodes at an opposite polarity via the switching assembly; and
  - ~~a switching assembly coupled to the workpiece electrode, the first remote electrode, the second remote electrode, the AC power supply, and the DC power supply, wherein the switching assembly is configured to selectively couple the AC power supply and/or the DC power supply to the workpiece electrode, the first remote electrode, and/or the second remote electrode.~~
2. (Previously presented) The apparatus of claim 1 wherein the workpiece electrode is carried by the workpiece holder.

3. (Previously presented) The apparatus of claim 1 wherein:  
the workpiece electrode is carried by the workpiece holder; and  
the first remote electrode and the second remote electrode are carried by a  
remote electrode assembly separate from the workpiece holder.
4. (Original) The apparatus of claim 1 wherein:  
the workpiece holder comprises a substrate carrier having a chuck configured to  
hold the workpiece so that the processing side faces downward and a  
drive assembly coupled to the substrate carrier to move the substrate  
carrier; and  
the workpiece electrode is carried by the workpiece holder.
5. (Original) The apparatus of claim 1 wherein:  
the workpiece holder comprises a substrate carrier having a chuck configured to  
hold the workpiece so that the processing side faces upward and a drive  
assembly coupled to the substrate carrier to move the substrate carrier;  
and  
the workpiece electrode is carried by the workpiece holder.
6. (Original) The apparatus of claim 1, further comprising an electrode  
assembly spaced apart from the workpiece holder, and wherein the first remote  
electrode and the second remote electrode are carried by the electrode assembly.
7. (Original) The apparatus of claim 1 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart  
from the workpiece holder, the electrode assembly being moveable  
relative to the workpiece holder; and  
the first remote electrode and the second remote electrode are carried by the  
electrode assembly.

8. (Original) The apparatus of claim 1 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart from the workpiece holder, the electrode assembly being moveable relative to the workpiece holder;  
the first remote electrode and the second remote electrode are carried by the electrode assembly; and  
the mechanical medium comprises a first polishing pad carried by the first remote electrode and a second polishing pad carried by the second remote electrode.

9. (Original) The apparatus of claim 1 wherein:  
the apparatus further comprises a table;  
the mechanical medium comprises a polishing pad carried by the table;  
the workpiece holder is positioned over the polishing pad, and the workpiece electrode is carried by the workpiece holder; and  
the first remote electrode and the second remote electrode are carried by the table.

10. (Original) The apparatus of claim 1, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrochemical processing solution, (b) applying a direct electrical current to the workpiece electrode and at least one of the first remote electrode and/or the second remote electrode while the workpiece contacts the electrochemical processing solution, (c) applying an alternating electrical current to at least one of the first remote electrode and/or the second remote electrode while the workpiece contacts the electrochemical processing solution, and (d) pressing the processing side of the workpiece against the mechanical medium at least while applying the alternating current.

11. (Original) The apparatus of claim 1, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrochemical processing solution, (b) applying a direct electrical current to the workpiece electrode and at least one of the first remote electrode and/or the second remote electrode while the workpiece contacts the electrochemical processing solution, (c) applying an alternating electrical current to the first remote electrode and the second remote electrode while the workpiece contacts the electrochemical processing solution, and (d) pressing the processing side of the workpiece against the mechanical medium at least while applying the alternating current.

12. (Original) The apparatus of claim 1, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrochemical processing solution, (b) applying a direct electrical current to the workpiece electrode and at least one of the first remote electrode and/or the second remote electrode while the workpiece contacts the electrochemical processing solution, (c) applying an alternating electrical current to the first remote electrode and the second remote electrode while applying the direct electrical current.

13. (Original) The apparatus of claim 1, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrochemical processing solution, (b) applying a direct electrical current to the workpiece electrode and at least one of the first remote electrode and/or the second remote electrode while the workpiece contacts the electrochemical processing solution, (c) applying an alternating electrical current to the first remote electrode and the second remote electrode while the workpiece contacts the electrochemical processing solution, (d) pressing the processing side of the

workpiece against the mechanical medium at least while applying the alternating current, and (e) moving the at least one of the workpiece and/or the first and second remote electrodes so that the first and the second remote electrodes have a higher dwell time at a first region of the workpiece than at a second region.

14. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

- a workpiece holder configured to receive a microelectronic workpiece;
- a workpiece electrode configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
- a first remote electrode and a second remote electrode, wherein the first and second remote electrodes are juxtaposed to the workpiece holder to be spaced apart from the processing side of the workpiece when the workpiece is received in the workpiece holder;
- an AC power supply;
- a DC power supply; and
- a switching assembly coupled to the workpiece electrode, the first remote electrode, the second remote electrode, the AC power supply, and the DC power supply, wherein the switching assembly ~~is configured to selectively couple the AC power supply and/or the DC power supply to the workpiece electrode, the first remote electrode, and/or the second remote electrode,~~ wherein the switching assembly includes at least a first configuration and a second configuration, and wherein in the first configuration, the DC power supply is coupled to the workpiece electrode and the first remote electrode while the AC power supply is simultaneously coupled to the first and second remote electrodes, and wherein in the second configuration, the DC power supply is connected to the workpiece electrode and both the first and second remote electrodes while simultaneously the AC power supply is coupled to the first and second remote electrodes.

15. (Original) The apparatus of claim 14 wherein the workpiece electrode is carried by the workpiece holder, and wherein the apparatus further comprises a mechanical medium having a bearing surface facing the workpiece holder and a backside facing the first and second remote electrodes.

16. (Original) The apparatus of claim 15 wherein:  
the workpiece electrode is carried by the workpiece holder; and  
the first remote electrode and the second remote electrode are carried by an electrode assembly separate from the workpiece holder.

17. (Original) The apparatus of claim 15, further comprising an electrode assembly spaced apart from the workpiece holder, and wherein the first and second remote electrodes are carried by the electrode assembly.

18. (Original) The apparatus of claim 15 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart from the workpiece holder, wherein the electrode assembly is moveable relative to the workpiece holder; and  
the first and second remote electrodes are carried by the electrode assembly.

19. (Original) The apparatus of claim 15 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart from the workpiece holder;  
the first and second remote electrodes are carried by the electrode assembly;  
and  
the mechanical medium comprises a first polishing pad carried by the first remote electrode and a second polishing pad carried by the second remote electrode.

20. (Original) The apparatus of claim 15 wherein:  
the apparatus further comprises a table;

the mechanical medium comprises a polishing pad carried by the table;  
the workpiece holder is positioned over the polishing pad, and the workpiece  
electrode is carried by the workpiece holder; and  
the first and second remote electrodes are carried by the table.

21. (Currently Amended). An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

- a workpiece holder configured to receive a microelectronic workpiece;
- a first electrode configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
- a second electrode and a third electrode, the second and third electrodes being remote electrodes that are spaced apart from the workpiece holder;
- a mechanical medium between the workpiece holder and each of the second and third electrodes;
- an AC power supply;
- a DC power supply; and
- a switching assembly coupled to the first electrode, second electrode, third electrode, AC power supply, and the DC power supply, wherein the switching assembly is configured to selectively couple the AC power supply and/or the DC power supply to the first, second, and/or third electrodes includes at least three configurations comprising:
  - a first configuration, wherein the DC power supply is disconnected from the workpiece electrode and the first and second remote electrodes while the AC power supply is coupled to the first and second remote electrodes;
  - a second configuration, wherein the DC power supply is coupled to the workpiece electrode and both the first and second remote electrodes while the AC power supply is disconnected from the first and second remote electrodes;
  - a third configuration, wherein the DC power supply is coupled to the workpiece electrode and both the first and second remote

electrodes while simultaneously the AC power supply is coupled to the first and second remote electrodes.

22. (Original) The apparatus of claim 21 wherein the first electrode is carried by the workpiece holder.

23. (Original) The apparatus of claim 21 wherein:  
the first electrode is carried by the workpiece holder; and  
the second and the third electrodes are carried by an electrode assembly separate from the workpiece holder.

24. (Original) The apparatus of claim 21 wherein:  
the workpiece holder comprises a substrate carrier having a chuck configured to hold the workpiece so that the processing side faces downward and a drive assembly coupled to the substrate carrier to move the substrate carrier; and  
the first electrode is carried by the workpiece holder.

25. (Original) The apparatus of claim 21 wherein:  
the workpiece holder comprises a substrate carrier having a chuck configured to hold the workpiece so that the processing side faces upward and a drive assembly coupled to the substrate carrier to move the substrate carrier;  
and  
the first electrode is carried by the workpiece holder.

26. (Original) The apparatus of claim 21, further comprising an electrode assembly spaced apart from the workpiece holder, and wherein the second and the third electrodes are carried by the electrode assembly.



27. (Original) The apparatus of claim 21 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart  
from the workpiece holder; and  
the second and the third electrodes are carried by the electrode assembly.

28. (Original) The apparatus of claim 21 wherein:  
the apparatus further comprises a moveable electrode assembly spaced apart  
from the workpiece holder;  
the second and the third electrodes are carried by the electrode assembly; and  
the mechanical medium comprises a first polishing pad carried by the second  
electrode and a second polishing pad carried by the third electrode.

29. (Original) The apparatus of claim 21 wherein:  
the apparatus further comprises a table;  
the mechanical medium comprises a polishing pad carried by the table;  
the workpiece holder is positioned over the polishing pad, and the first electrode  
is carried by the workpiece holder; and  
the second and the third electrodes are carried by the table.

30. (Original) The apparatus of claim 21, further comprising a controller  
having a computer operable medium containing instructions to operate the apparatus  
according to a process comprising (a) contacting the processing side of the  
microelectronic workpiece with an electrolytic solution, (b) applying a direct electrical  
current to the first electrode and at least one of the second and/or the third electrodes  
while the workpiece contacts the electrolytic solution, (c) applying an alternating  
electrical current to at least one of the second and/or the third electrodes while the  
workpiece contacts the electrolytic solution, and (d) pressing the processing side of the  
workpiece against the mechanical medium at least while applying the alternating  
current.

31. (Original) The apparatus of claim 21, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrolytic solution, (b) applying a direct electrical current to the first electrode and at least one of the second and/or the third electrodes while the workpiece contacts the electrolytic solution, (c) applying an alternating electrical current to the second and the third electrodes while the workpiece contacts the electrolytic solution, and (d) pressing the processing side of the workpiece against the mechanical medium at least while applying the alternating current.

32. (Original) The apparatus of claim 21, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrolytic solution, (b) applying a direct electrical current to the first electrode and at least one of the second and/or the third electrodes while the workpiece contacts the electrolytic solution, (c) applying an alternating electrical current to the second and the third electrodes while applying the direct electrical current.

33. (Original) The apparatus of claim 21, further comprising a controller having a computer operable medium containing instructions to operate the apparatus according to a process comprising (a) contacting the processing side of the microelectronic workpiece with an electrolytic solution, (b) applying a direct electrical current to the first electrode and at least one of the second and/or the third electrodes while the workpiece contacts the electrolytic solution, (c) applying an alternating electrical current to the second and the third electrodes while the workpiece contacts the electrolytic solution, (d) pressing the processing side of the workpiece against the mechanical medium at least while applying the alternating current, and (e) moving the at least one of the workpiece and/or the second and third electrodes so that the second and the third electrodes have a higher dwell time at a first region of the workpiece than at a second region.

34. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

- a workpiece holder configured to receive a microelectronic workpiece;
- a workpiece electrode configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
- a first remote electrode and a second remote electrode, the first and second remote electrodes being spaced apart from the workpiece holder;
- a mechanical medium between the workpiece holder and each of the first and second remote electrodes;
- an AC power supply;
- a DC power supply; and
- a switching assembly coupled to the workpiece electrode, first remote electrode, second remote electrode, AC power supply, and the DC power supply; and
- a controller coupled to the switching assembly, the controller including a computer operable medium containing instructions to operate the switching assembly according to a process including (a) coupling the workpiece electrode and at least one of the first and second remote electrodes to the DC power supply via the switching assembly, and/or (b) coupling the first and second remote electrodes to the AC power supply via the switching assembly.

35. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

- a workpiece holder configured to receive a microelectronic workpiece;
- a workpiece electrode configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
- a first remote electrode and a second remote electrode, the first and second remote electrodes being spaced apart from the workpiece holder;
- a mechanical medium between the workpiece holder and each of the first and second remote electrodes;

a switching assembly coupled to the workpiece electrode, first remote electrode, and second remote electrode;  
an AC power supply electrically coupled to the switching assembly to be in electrical communication with the first and second remote electrodes; and  
a DC power supply electrically coupled to the switching assembly to be in electrical communication with the workpiece electrode at one polarity and at least one of the first and second remote electrodes at an opposite polarity via the switching assembly; and  
~~a switching assembly coupled to the workpiece electrode, first remote electrode, second remote electrode, AC power supply, and the DC power supply, wherein the switching assembly is configured to selectively couple the workpiece electrode and at least one of the first and/or second remote electrodes to the DC power supply, and further wherein the switching assembly is configured to selectively couple at least the first and second remote electrodes to the AC power supply.~~

36. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

- a workpiece holder configured to receive a microelectronic workpiece;
- a workpiece electrode carried by the workpiece holder, the workpiece electrode being configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;
- a material removal device including an electrode assembly facing the workpiece holder, a first remote electrode carried by the electrode assembly, a second remote electrode carried by the electrode assembly, and a mechanical medium carried by the first and second remote electrodes, wherein the first and second remote electrodes are spaced apart from the workpiece holder;
- an AC power supply;
- a DC power supply; and

a switching assembly coupled to the workpiece electrode, first remote electrode, second remote electrode, AC power supply, and the DC power supply, wherein the switching assembly is configured to selectively couple the AC power supply and/or the DC power supply to the workpiece electrode, the first remote electrode, and/or the second remote electrode includes at least three configurations comprising:

a first configuration, wherein the DC power supply is disconnected from the workpiece electrode and the first and second remote electrodes while the AC power supply is coupled to the first and second remote electrodes;

a second configuration, wherein the DC power supply is coupled to the workpiece electrode and both the first and second remote electrodes while the AC power supply is disconnected from the first and second remote electrodes;

a third configuration, wherein the DC power supply is coupled to the workpiece electrode and both the first and second remote electrodes while simultaneously the AC power supply is coupled to the first and second remote electrodes.

37. (Currently Amended) An apparatus for electrochemical-mechanical processing of microelectronic workpieces, comprising:

a workpiece holder configured to receive a microelectronic workpiece;

a workpiece electrode carried by the workpiece holder, the workpiece electrode being configured to contact a processing side of the workpiece when the workpiece is received in the workpiece holder;

a material removal device including an electrode assembly facing the workpiece holder, a first remote electrode carried by the electrode assembly, a second remote electrode carried by the electrode assembly, and a mechanical medium carried by the first and second remote electrodes, wherein the electrode assembly is moveable to move the first and second remote electrodes relative to the workpiece holder;

an AC power supply;  
a DC power supply; and  
a switching assembly coupled to the workpiece electrode, first remote electrode, second remote electrode, AC power supply, and the DC power supply, wherein the switching assembly is configured to selectively couple the AC power supply and/or the DC power supply to the workpiece electrode, the first remote electrode, and/or the second remote electrode includes at least two configurations comprising:  
a first configuration, wherein the DC power supply is coupled to the workpiece electrode and the first remote electrode while the AC power supply is coupled to the first and second remote electrodes;  
a second configuration, wherein the DC power supply is coupled to the workpiece electrode and the second remote electrode while simultaneously the AC power supply is coupled to the first and second remote electrodes.

38. (Currently Amended) A method of electrochemical-mechanical processing of microelectronic workpieces, comprising:

contacting a processing side of a microelectronic workpiece with an electrolytic solution;  
applying a direct electrical current to a workpiece electrode contacting the processing side of the workpiece and a first remote electrode spaced apart from the processing side of the workpiece, the workpiece electrode and the first remote electrode being in electrical communication with the electrolytic solution;  
applying an alternating current to the first remote electrode and a second remote electrode also spaced apart from the processing side of the workpiece, the first and second remote electrodes being in electrical communication with the electrolytic solution; and

contacting the processing side of the workpiece with a mechanical medium at least while applying the alternating current to the first and second remote electrodes.

39. (Currently Amended) A method of electrochemical-mechanical processing of microelectronic workpieces, comprising:

contacting a processing side of a microelectronic workpiece with an electrolytic solution;

applying a direct electrical current to a workpiece electrode contacting the processing side of the workpiece and at least one of a first remote electrode and/or a second remote electrode spaced apart from the processing side of the workpiece, the workpiece electrode, the first remote electrode, and the second remote electrode being in electrical communication with the electrolytic solution;

applying an alternating current to the first and second remote electrodes; and

contacting the processing side of the workpiece with a mechanical medium at least while applying the alternating current to the first and second remote electrodes.

40. (Currently Amended) A method of electrochemical-mechanical processing of microelectronic workpieces, comprising:

contacting a processing side of a microelectronic workpiece with an electrolytic solution;

applying a direct electrical current to a workpiece electrode in contact with the processing side of the workpiece and at least one of a first remote electrode and/or a second remote electrode, wherein the workpiece electrode, the first remote electrode, and the second remote electrode are in electrical communication with the electrolytic solution; and

applying an alternating current to the first and second remote electrodes while applying the direct current to the workpiece electrode and at least one of the first remote electrode and/or a second remote electrode.

41. (Currently Amended) A method of electrochemical-mechanical processing of microelectronic workpieces, comprising:

contacting a processing side of a microelectronic workpiece with an electrolytic solution;

applying a direct electrical current to a workpiece electrode contacting the processing side of the workpiece and at least one of a first remote electrode and/or a second remote electrode spaced apart from the processing side of the workpiece, and simultaneously applying an alternating current to the first and second remote electrodes, wherein the workpiece electrode, the first remote electrode, and the second remote electrode being are in electrical communication with the electrolytic solution;

~~applying an alternating current to the first and second remote electrodes while applying the direct current; and~~

moving at least one of the microelectronic workpiece and/or the first and second remote electrodes relative to each other while applying the direct current and the alternating current so that the first and second remote electrodes have a higher dwell time at a first region of the workpiece than at a second region of the workpiece.

42. (Currently Amended) A method of electrochemical-mechanical processing of microelectronic workpieces, comprising:

contacting a processing side of a microelectronic workpiece with an electrolytic solution;

applying a direct electrical current to a workpiece electrode that is in contact with the processing side of the workpiece and at least one of a first remote electrode and/or a second remote electrode, the workpiece electrode, the first remote electrode and simultaneously applying an alternating current to the first and second remote electrodes, wherein and the second remote electrode ~~being are~~ in electrical communication with the electrolytic solution;



~~applying an alternating current to the first and second remote electrodes while~~  
~~applying the direct current; and~~  
moving at least one of the microelectronic workpiece and/or the first and second  
remote electrodes relative to each other while applying the direct current  
and the alternating current so that the first and second remote electrodes  
have a higher dwell time at regions of the workpiece having a thicker layer  
of a plated material.